

Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	121
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	152-VFBGA
Supplier Device Package	152-BGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b840f1024gl152-b

1. Feature List

The EFM32GG11 highlighted features are listed below.

- **ARM Cortex-M4 CPU platform**
 - High performance 32-bit processor @ up to 72 MHz
 - DSP instruction support and Floating Point Unit
 - Memory Protection Unit
 - Wake-up Interrupt Controller
- **Flexible Energy Management System**
 - 80 μ A/MHz in Active Mode (EM0)
 - 2.1 μ A EM2 Deep Sleep current (16 kB RAM retention and RTCC running from LFRCO)
- **Integrated DC-DC buck converter**
- **Up to 2048 kB flash program memory**
 - Dual-bank with read-while-write support
- **Up to 512 kB RAM data memory**
 - 256 kB with ECC (SEC-DED)
- **Octal/Quad-SPI Flash Memory Interface**
 - Supports 3 V and 1.8 V memories
 - 1/2/4/8-bit data bus
 - Quad-SPI Execute In Place (XIP)
- **Communication Interfaces**
 - Low-energy Universal Serial Bus (USB) with Device and Host support
 - Fully USB 2.0 compliant
 - On-chip PHY and embedded 5V to 3.3V regulator
 - Crystal-free Device mode operation
 - Patent-pending Low-Energy Mode (LEM)
 - SD/MMC/SDIO Host Controller
 - SD v3.01, SDIO v3.0 and MMC v4.51
 - 1/4/8-bit bus width
 - 10/100 Ethernet MAC with MII/RMII interface
 - IEEE1588-2008 precision time stamping
 - Energy Efficient Ethernet (802.3az)
 - Up to 2 $\times$ CAN Bus Controller
 - Version 2.0A and 2.0B up to 1 Mbps
 - 6 $\times$ Universal Synchronous/Asynchronous Receiver/ Transmitter
 - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S/LIN
 - Triple buffered full/half-duplex operation with flow control
 - Ultra high speed (36 MHz) operation on one instance
 - 2 $\times$ Universal Asynchronous Receiver/ Transmitter
 - 2 $\times$ Low Energy UART
 - Autonomous operation with DMA in Deep Sleep Mode
 - 3 $\times$ I²C Interface with SMBus support
 - Address recognition in EM3 Stop Mode
- **Up to 144 General Purpose I/O Pins**
 - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
 - Configurable peripheral I/O locations
 - 5 V tolerance on select pins
 - Asynchronous external interrupts
 - Output state retention and wake-up from Shutoff Mode
- **Up to 24 Channel DMA Controller**
- **Up to 24 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling**
- **External Bus Interface for up to 4x256 MB of external memory mapped space**
 - TFT Controller with Direct Drive
 - Per-pixel alpha-blending engine
- **Hardware Cryptography**
 - AES 128/256-bit keys
 - ECC B/K163, B/K233, P192, P224, P256
 - SHA-1 and SHA-2 (SHA-224 and SHA-256)
 - True Random Number Generator (TRNG)
- **Hardware CRC engine**
 - Single-cycle computation with 8/16/32-bit data and 16-bit (programmable)/32-bit (fixed) polynomial
- **Security Management Unit (SMU)**
 - Fine-grained access control for on-chip peripherals
- **Integrated Low-energy LCD Controller with up to 8 $\times$ 36 segments**
 - Voltage boost, contrast and autonomous animation
 - Patented low-energy LCD driver
- **Backup Power Domain**
 - RTCC and retention registers in a separate power domain, available down to energy mode EM4H
 - Operation from backup battery when main power absent/ insufficient
- **Ultra Low-Power Precision Analog Peripherals**
 - 2 $\times$ 12-bit 1 Msamples/s Analog to Digital Converter (ADC)
 - On-chip temperature sensor
 - 2 $\times$ 12-bit 500 ksamples/s Digital to Analog Converter (VDAC)
 - Digital to Analog Current Converter (IDAC)
 - Up to 4 $\times$ Analog Comparator (ACMP)
 - Up to 4 $\times$ Operational Amplifier (OPAMP)
 - Robust current-based capacitive sensing with up to 64 inputs and wake-on-touch (CSEN)
 - Up to 108 GPIO pins are analog-capable. Flexible analog peripheral-to-pin routing via Analog Port (APORT)
 - Supply Voltage Monitor

3.12 Configuration Summary

The features of the EFM32GG11 are a subset of the feature set described in the device reference manual. The table below describes device specific implementation of the features. Remaining modules support full configuration.

Table 3.2. Configuration Summary

Module	Configuration	Pin Connections
USART0	IrDA, SmartCard	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	I ² S, SmartCard	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	IrDA, SmartCard, High-Speed	US2_TX, US2_RX, US2_CLK, US2_CS
USART3	I ² S, SmartCard	US3_TX, US3_RX, US3_CLK, US3_CS
USART4	I ² S, SmartCard	US4_TX, US4_RX, US4_CLK, US4_CS
USART5	SmartCard	US5_TX, US5_RX, US5_CLK, US5_CS
TIMER0	with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	-	TIM1_CC[3:0]
TIMER2	with DTI	TIM2_CC[2:0], TIM2_CDTI[2:0]
TIMER3	-	TIM3_CC[2:0]
TIMER4	with DTI	TIM4_CC[2:0], TIM4_CDTI[2:0]
TIMER5	-	TIM5_CC[2:0]
TIMER6	with DTI	TIM6_CC[2:0], TIM6_CDTI[2:0]
WTIMER0	with DTI	WTIM0_CC[2:0], WTIM0_CDTI[2:0]
WTIMER1	-	WTIM1_CC[3:0]
WTIMER2	-	WTIM2_CC[2:0]
WTIMER3	-	WTIM3_CC[2:0]

4.1.1 Absolute Maximum Ratings

Stresses above those listed below may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at <http://www.silabs.com/support/quality/pages/default.aspx>.

Table 4.1. Absolute Maximum Ratings

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Storage temperature range	T _{STG}		-50	—	150	°C
Voltage on supply pins other than VREGI and VBUS	V _{DDMAX}		-0.3	—	3.8	V
Voltage ramp rate on any supply pin	V _{DDRAMP} MAX		—	—	1	V / μ s
DC voltage on any GPIO pin	V _{DIGPIN}	5V tolerant GPIO pins ^{1 2 3}	-0.3	—	Min of 5.25 and IOVDD +2	V
		LCD pins ³	-0.3	—	Min of 3.8 and IOVDD +2	V
		Standard GPIO pins	-0.3	—	IOVDD+0.3	V
Total current into VDD power lines	I _{VDDMAX}	Source	—	—	200	mA
Total current into VSS ground lines	I _{VSSMAX}	Sink	—	—	200	mA
Current per I/O pin	I _{IOMAX}	Sink	—	—	50	mA
		Source	—	—	50	mA
Current for all I/O pins	I _{IOALLMAX}	Sink	—	—	200	mA
		Source	—	—	200	mA
Junction temperature	T _J	-G grade devices	-40	—	105	°C
		-I grade devices	-40	—	125	°C
Voltage on regulator supply pins VREGI and VBUS	V _{VREGI}		-0.3	—	5.5	V

Note:

1. When a GPIO pin is routed to the analog module through the APORT, the maximum voltage = IOVDD.
2. Valid for IOVDD in valid operating range or when IOVDD is undriven (high-Z). If IOVDD is connected to a low-impedance source below the valid operating range (e.g. IOVDD shorted to VSS), the pin voltage maximum is IOVDD + 0.3 V, to avoid exceeding the maximum IO current specifications.
3. To operate above the IOVDD supply rail, over-voltage tolerance must be enabled according to the GPIO_Px_OVTDIS register. Pins with over-voltage tolerance disabled have the same limits as Standard GPIO.

4.1.7.2 Current Consumption 3.3 V using DC-DC Converter

Unless otherwise indicated, typical conditions are: VREGVDD = AVDD = IOVDD = 3.3 V, DVDD = 1.8 V DC-DC output. T = 25 °C. Minimum and maximum values in this table represent the worst conditions across supply voltage and process variation at T = 25 °C.

Table 4.8. Current Consumption 3.3 V using DC-DC Converter

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled, DCDC in Low Noise DCM mode ²	I _{ACTIVE_DCM}	72 MHz HFRCO, CPU running Prime from flash	—	80	—	μA/MHz
		72 MHz HFRCO, CPU running while loop from flash	—	80	—	μA/MHz
		72 MHz HFRCO, CPU running CoreMark loop from flash	—	92	—	μA/MHz
		50 MHz crystal, CPU running while loop from flash	—	84	—	μA/MHz
		48 MHz HFRCO, CPU running while loop from flash	—	84	—	μA/MHz
		32 MHz HFRCO, CPU running while loop from flash	—	90	—	μA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	94	—	μA/MHz
		16 MHz HFRCO, CPU running while loop from flash	—	109	—	μA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	698	—	μA/MHz
Current consumption in EM0 mode with all peripherals disabled, DCDC in Low Noise CCM mode ¹	I _{ACTIVE_CCM}	72 MHz HFRCO, CPU running Prime from flash	—	84	—	μA/MHz
		72 MHz HFRCO, CPU running while loop from flash	—	84	—	μA/MHz
		72 MHz HFRCO, CPU running CoreMark loop from flash	—	95	—	μA/MHz
		50 MHz crystal, CPU running while loop from flash	—	91	—	μA/MHz
		48 MHz HFRCO, CPU running while loop from flash	—	92	—	μA/MHz
		32 MHz HFRCO, CPU running while loop from flash	—	104	—	μA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	113	—	μA/MHz
		16 MHz HFRCO, CPU running while loop from flash	—	142	—	μA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	1264	—	μA/MHz

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency limits	f _{HFRCO_BAND}	FREQRANGE = 0, FINETUNING = 0	1	—	10	MHz
		FREQRANGE = 3, FINETUNING = 0	2	—	17	MHz
		FREQRANGE = 6, FINETUNING = 0	4	—	30	MHz
		FREQRANGE = 7, FINETUNING = 0	5	—	34	MHz
		FREQRANGE = 8, FINETUNING = 0	7	—	42	MHz
		FREQRANGE = 10, FINETUNING = 0	12	—	58	MHz
		FREQRANGE = 11, FINETUNING = 0	15	—	68	MHz
		FREQRANGE = 12, FINETUNING = 0	18	—	83	MHz
		FREQRANGE = 13, FINETUNING = 0	24	—	100	MHz
		FREQRANGE = 14, FINETUNING = 0	28	—	119	MHz
		FREQRANGE = 15, FINETUNING = 0	33	—	138	MHz
		FREQRANGE = 16, FINETUNING = 0	43	—	163	MHz
Note: 1. Maximum DPLL lock time ~ = 6 x (M+1) x t _{REF} , where t _{REF} is the reference clock period.						

4.1.23 I2C

4.1.23.1 I2C Standard-mode (Sm)¹

Table 4.31. I2C Standard-mode (Sm)¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SCL clock frequency ²	f _{SCL}		0	—	100	kHz
SCL clock low time	t _{LOW}		4.7	—	—	μs
SCL clock high time	t _{HIGH}		4	—	—	μs
SDA set-up time	t _{SU_DAT}		250	—	—	ns
SDA hold time ³	t _{HD_DAT}		100	—	3450	ns
Repeated START condition set-up time	t _{SU_STA}		4.7	—	—	μs
(Repeated) START condition hold time	t _{HD_STA}		4	—	—	μs
STOP condition set-up time	t _{SU_STO}		4	—	—	μs
Bus free time between a STOP and START condition	t _{BUF}		4.7	—	—	μs

Note:

1. For CLHR set to 0 in the I2Cn_CTRL register.
2. For the minimum HPERCLK frequency required in Standard-mode, refer to the I2C chapter in the reference manual.
3. The maximum SDA hold time (t_{HD_DAT}) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
MISO hold time ^{1 3}	t_{H_MI}	USART2, location 4, IOVDD = 1.8 V	-11.6	—	—	ns
		USART2, location 4, IOVDD = 3.0 V	-11.6	—	—	ns
		USART2, location 5, IOVDD = 1.8 V	-9.1	—	—	ns
		USART2, location 5, IOVDD = 3.0 V	-9.1	—	—	ns
		All other USARTs and locations, IOVDD = 1.8 V	-8	—	—	ns
		All other USARTs and locations, IOVDD = 3.0 V	-8	—	—	ns

Note:

1. Applies for both CLKPHA = 0 and CLKPHA = 1 (figure only shows CLKPHA = 0).
2. t_{H_PERCLK} is one period of the selected HPERCLK.
3. Measurement done with 8 pF output loading at 10% and 90% of V_{DD} (figure shows 50% of V_{DD}).

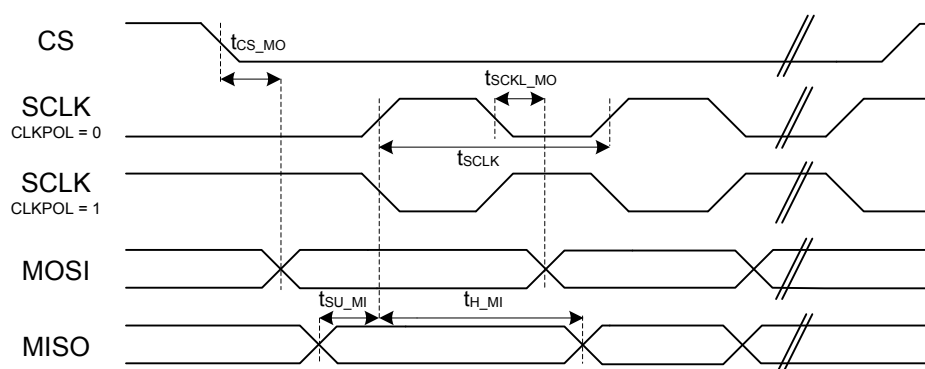


Figure 4.1. SPI Master Timing Diagram

SDIO SDR Mode Timing

Timing is specified for route location 0 at 1.8 V IOVDD with voltage scaling disabled. Slew rate for SD_CLK set to 7, all other GPIO set to 6, DRIVESTRENGTH = STRONG for all pins. SDIO_CTRL_TXDLYMUXSEL = 0. Loading between 5 and 10 pF on all pins or between 10 and 40 pF on all pins.

Table 4.48. SDIO SDR Mode Timing (Location 0)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Clock frequency during data transfer	F_{SD_CLK}	Using HFRCO, AUXHFRCO, or USHFRCO	—	—	20	MHz
		Using HFXO	—	—	TBD	MHz
Clock low time	t_{WL}	Using HFRCO, AUXHFRCO, or USHFRCO	22.6	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock high time	t_{WH}	Using HFRCO, AUXHFRCO, or USHFRCO	22.6	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock rise time	t_R		0.99	4.68	—	ns
Clock fall time	t_F		0.90	3.64	—	ns
Input setup time, CMD, DAT[0:3] valid to SD_CLK	t_{ISU}		8	—	—	ns
Input hold time, SD_CLK to CMD, DAT[0:3] change	t_{IH}		1.5	—	—	ns
Output delay time, SD_CLK to CMD, DAT[0:3] valid	t_{ODLY}		0	—	35	ns
Output hold time, SD_CLK to CMD, DAT[0:3] change	t_{OH}		0.8	—	—	ns

SDIO DDR Mode Timing

Timing is specified for route location 0 at 1.8 V IOVDD with voltage scaling disabled. Slew rate for SD_CLK set to 6, all other GPIO set to 6, DRIVESTRENGTH = STRONG for all pins. SDIO_CTRL_TXDLYMUXSEL = 1. Loading between 5 and 10 pF on all pins or between 10 and 30 pF on all pins.

Table 4.49. SDIO DS Mode Timing (Location 0)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Clock frequency during data transfer	F_{SD_CLK}	Using HFRCO, AUXHFRCO, or USHFRCO	—	—	20	MHz
		Using HFXO	—	—	TBD	MHz
Clock low time	t_{WL}	Using HFRCO, AUXHFRCO, or USHFRCO	22.6	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock high time	t_{WH}	Using HFRCO, AUXHFRCO, or USHFRCO	22.6	—	—	ns
		Using HFXO	TBD	—	—	ns
Clock rise time	t_R		1.69	6.52	—	ns
Clock fall time	t_F		1.42	4.96	—	ns
Input setup time, CMD valid to SD_CLK	t_{ISU}		6	—	—	ns
Input hold time, SD_CLK to CMD change	t_{IH}		1.8	—	—	ns
Output delay time, SD_CLK to CMD valid	t_{ODLY}		0	—	16	ns
Output hold time, SD_CLK to CMD change	t_{OH}		0.8	—	—	ns
Input setup time, DAT[0:3] valid to SD_CLK	t_{ISU2X}		6	—	—	ns
Input hold time, SD_CLK to DAT[0:3] change	t_{IH2X}		1.5	—	—	ns
Output delay time, SD_CLK to DAT[0:3] valid	t_{ODLY2X}		0	—	16	ns
Output hold time, SD_CLK to DAT[0:3] change	t_{OH2X}		0.8	—	—	ns

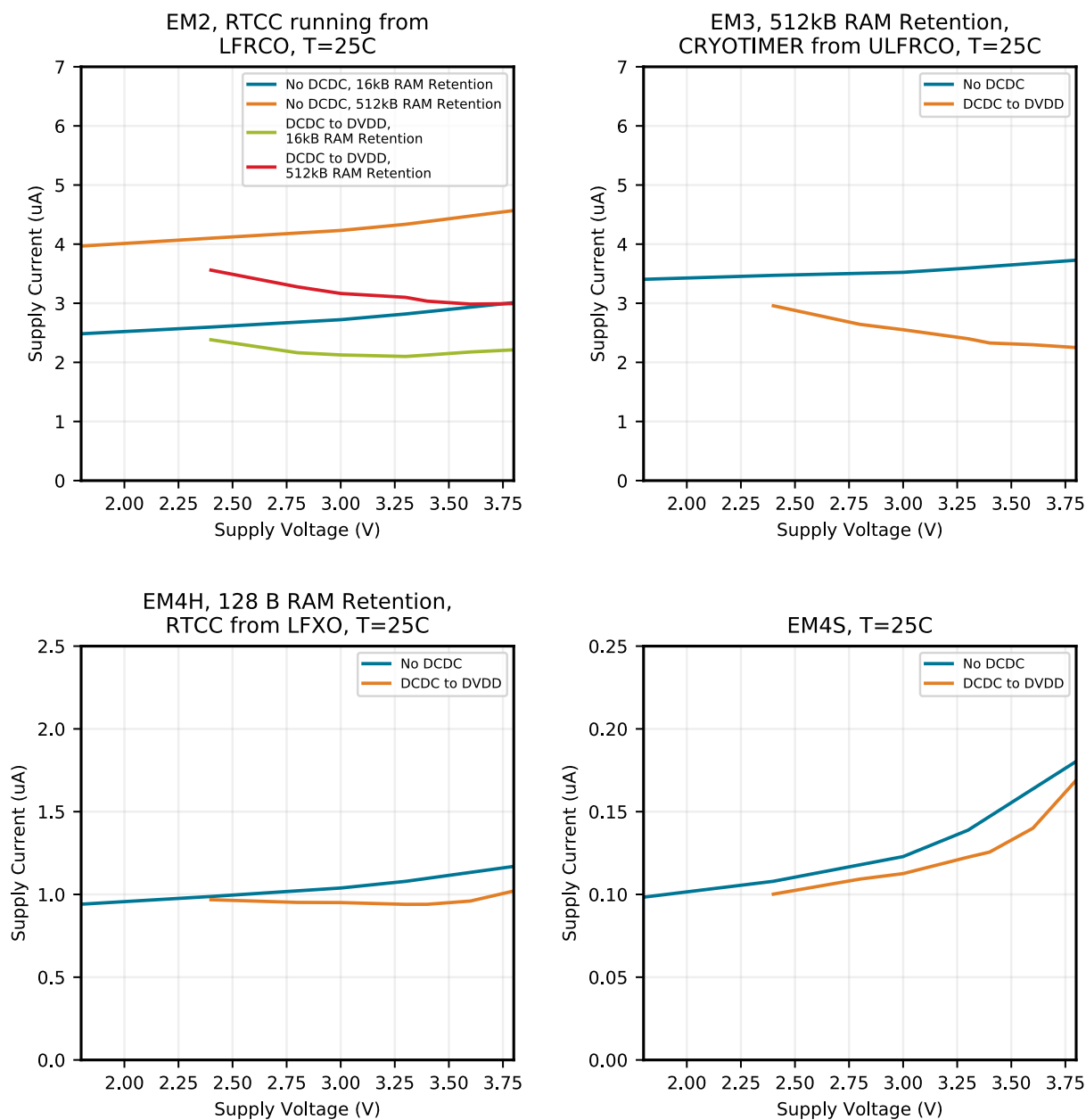


Figure 4.28. EM2, EM3, EM4H and EM4S Typical Supply Current vs. Supply

4.2.2 DC-DC Converter

Default test conditions: CCM mode, LDCDC = 4.7 μ H, CDCDC = 4.7 μ F, VDCDC_I = 3.3 V, VDCDC_O = 1.8 V, FDCDC_LN = 7 MHz

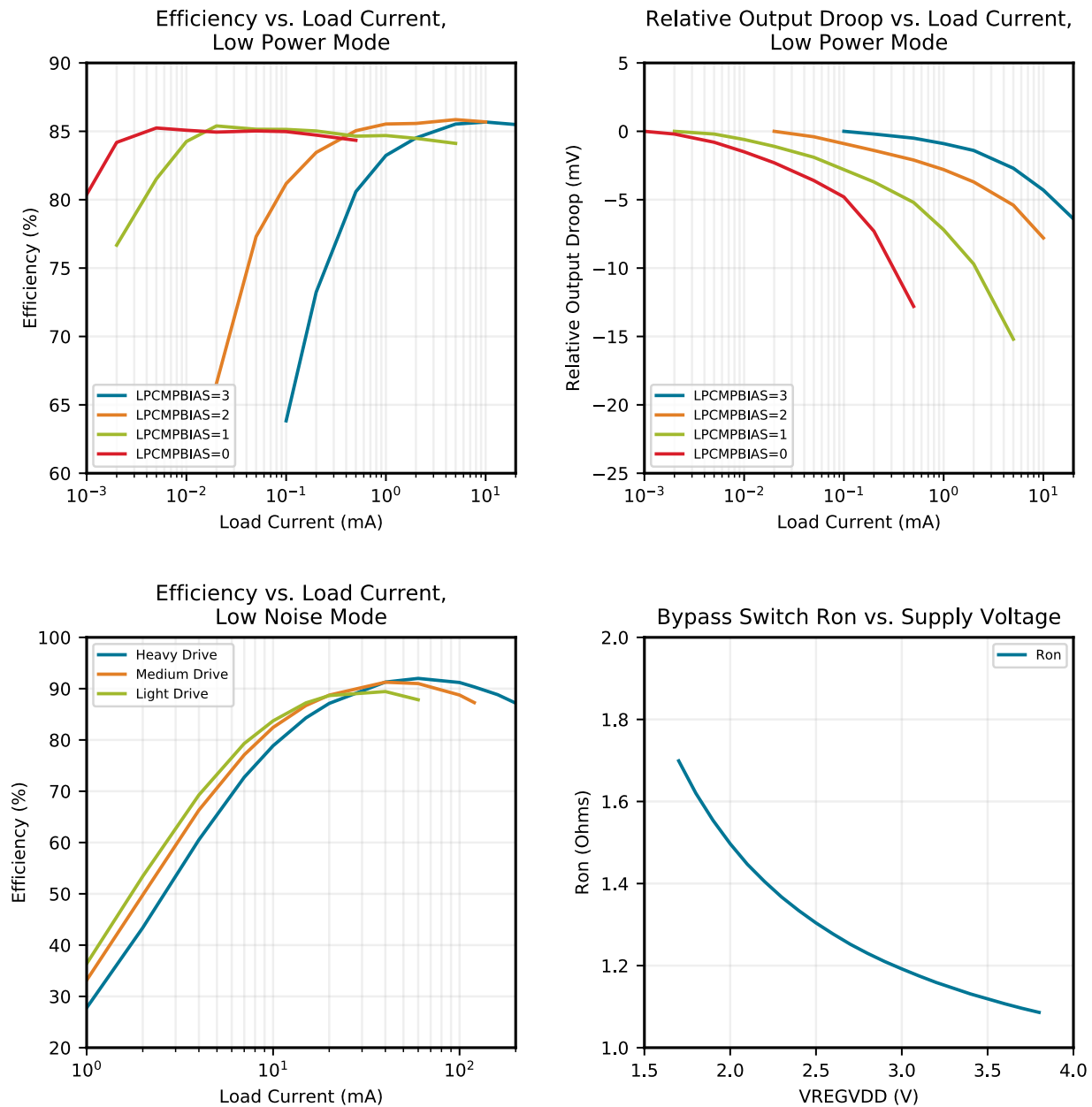


Figure 4.29. DC-DC Converter Typical Performance Characteristics

5. Pin Definitions

5.1 EFM32GG11B8xx in BGA192 Device Pinout

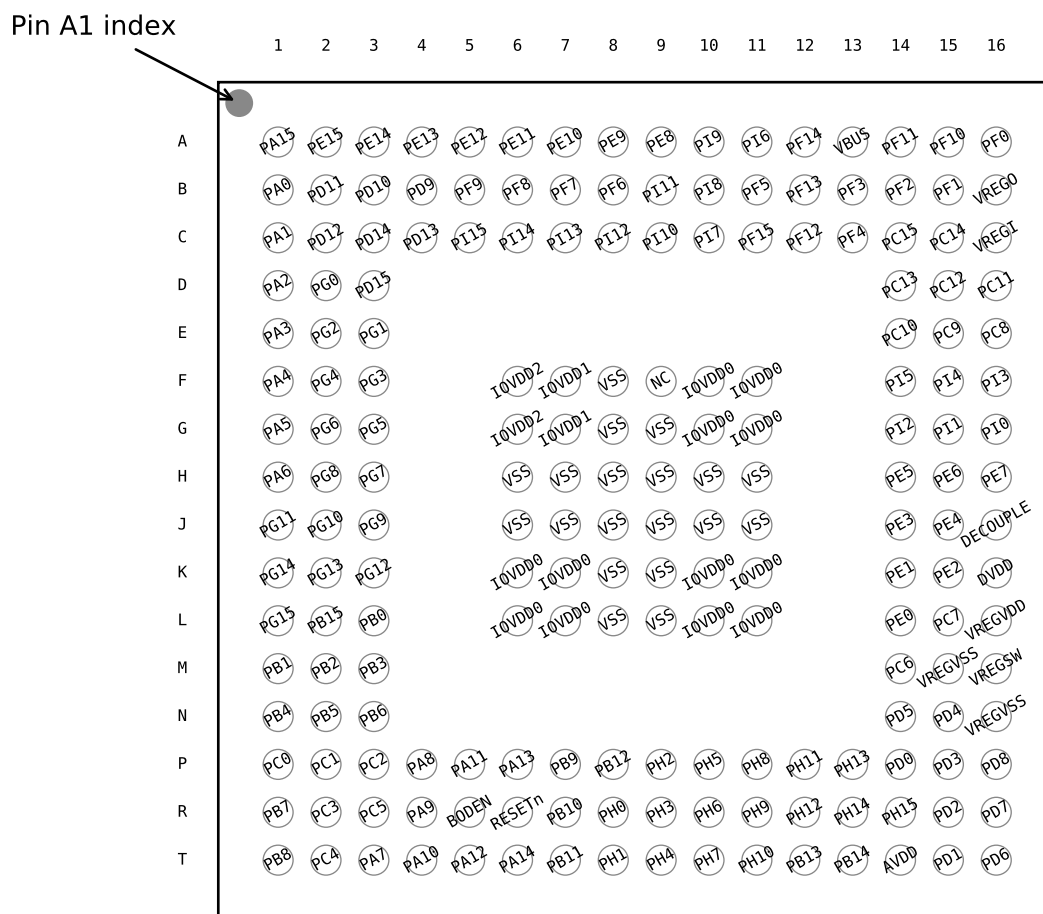


Figure 5.1. EFM32GG11B8xx in BGA192 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.1. EFM32GG11B8xx in BGA192 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA15	A1	GPIO	PE15	A2	GPIO
PE14	A3	GPIO	PE13	A4	GPIO
PE12	A5	GPIO	PE11	A6	GPIO
PE10	A7	GPIO	PE9	A8	GPIO
PE8	A9	GPIO	PI9	A10	GPIO (5V)
PI6	A11	GPIO (5V)	PF14	A12	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PD15	J2	GPIO (5V)	PC6	J12	GPIO
DECOUPLE	J13	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PC0	K1	GPIO (5V)
PC1	K2	GPIO (5V)	PD8	K13	GPIO
PC2	L1	GPIO (5V)	PC3	L2	GPIO (5V)
PA7	L3	GPIO	PB9	L15	GPIO (5V)
PB10	L16	GPIO (5V)	PD0	L17	GPIO (5V)
PD1	L18	GPIO	PD4	L19	GPIO
PD7	L20	GPIO	PB7	M1	GPIO
PC4	M2	GPIO	PA8	M3	GPIO
PA10	M4	GPIO	PA13	M5	GPIO (5V)
PA14	M6	GPIO	RESETn	M7	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
AVDD	M9 M10 N11	Analog power supply.	PD3	M12	GPIO
PD6	M13	GPIO	PB8	N1	GPIO
PC5	N2	GPIO	PA9	N3	GPIO
PA11	N4	GPIO	PA12	N5	GPIO (5V)
PB11	N6	GPIO	PB12	N7	GPIO
PB13	N9	GPIO	PB14	N10	GPIO
PD2	N12	GPIO (5V)	PD5	N13	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).
2. The pins PD13, PD14, and PD15 will not be 5V tolerant on all future devices. In order to preserve upgrade options with full hardware compatibility, do not use these pins with 5V domains.

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PB2	11	GPIO	PB3	12	GPIO
PB4	13	GPIO	PB5	14	GPIO
PB6	15	GPIO	VSS	16 32 59 83	Ground
PC0	18	GPIO (5V)	PC1	19	GPIO (5V)
PC2	20	GPIO (5V)	PC3	21	GPIO (5V)
PC4	22	GPIO	PC5	23	GPIO
PB7	24	GPIO	PB8	25	GPIO
PA7	26	GPIO	PA8	27	GPIO
PA9	28	GPIO	PA10	29	GPIO
PA11	30	GPIO	PA12	33	GPIO (5V)
PA13	34	GPIO (5V)	PA14	35	GPIO
RESETn	36	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB9	37	GPIO (5V)
PB10	38	GPIO (5V)	PB11	39	GPIO
PB12	40	GPIO	AVDD	41	Analog power supply.
PB13	42	GPIO	PB14	43	GPIO
PD0	45	GPIO (5V)	PD1	46	GPIO
PD2	47	GPIO (5V)	PD3	48	GPIO
PD4	49	GPIO	PD5	50	GPIO
PD6	51	GPIO	PD7	52	GPIO
PD8	53	GPIO	PC7	54	GPIO
VREGVSS	55	Voltage regulator VSS	VREGSW	56	DCDC regulator switching node
VREGVDD	57	Voltage regulator VDD input	DVDD	58	Digital power supply.
DECOUPLE	60	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PE1	61	GPIO (5V)
PE2	62	GPIO	PE3	63	GPIO
PE4	64	GPIO	PE5	65	GPIO
PE6	66	GPIO	PE7	67	GPIO
PC8	68	GPIO (5V)	PC9	69	GPIO (5V)
PC10	70	GPIO (5V)	PC11	71	GPIO (5V)
VREGI	72	Input to 5 V regulator.	VREGO	73	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs
PF10	74	GPIO (5V)	PF11	75	GPIO (5V)
PF0	76	GPIO (5V)	PF1	77	GPIO (5V)

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC4	13	GPIO	PC5	14	GPIO
PB7	15	GPIO	PB8	16	GPIO
PA8	17	GPIO	PA12	18	GPIO (5V)
PA14	19	GPIO	RESETn	20	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	21	GPIO	PB12	22	GPIO
AVDD	24	Analog power supply.	PB13	25	GPIO
PB14	26	GPIO	PD0	28	GPIO (5V)
PD1	29	GPIO	PD2	30	GPIO (5V)
PD3	31	GPIO	PD4	32	GPIO
PD5	33	GPIO	PD6	34	GPIO
PD8	35	GPIO	VREGVSS	36	Voltage regulator VSS
VREGSW	37	DCDC regulator switching node	VREGVDD	38	Voltage regulator VDD input
DVDD	39	Digital power supply.	DECOUPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.
PE4	41	GPIO	PE5	42	GPIO
PE6	43	GPIO	PE7	44	GPIO
VREGI	45	Input to 5 V regulator.	VREGO	46	Decoupling for 5 V regulator and regulator output. Power for USB PHY in USB-enabled OPNs
PF10	47	GPIO (5V)	PF11	48	GPIO (5V)
PF0	49	GPIO (5V)	PF1	50	GPIO (5V)
PF2	51	GPIO	VBUS	52	USB VBUS signal and auxiliary input to 5 V regulator.
PF12	53	GPIO	PF5	54	GPIO
PE8	57	GPIO	PE9	58	GPIO
PE10	59	GPIO	PE11	60	GPIO
PE12	61	GPIO	PE13	62	GPIO
PE14	63	GPIO	PE15	64	GPIO

Note:

1. GPIO with 5V tolerance are indicated by (5V).

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
EBI_CS1	0: PD10 1: PA11 2: PC1 3: PB1	4: PE9	External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	0: PD11 1: PA12 2: PC2 3: PB2	4: PE10	External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	0: PD12 1: PB15 2: PC3 3: PB3	4: PE11	External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	0: PA7 1: PF6 2: PB12 3: PA0		External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	0: PA8 1: PF7 2: PH0 3: PA1		External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	0: PA9 1: PD9 2: PH1 3: PA2		External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNCR	0: PA11 1: PD11 2: PH3 3: PA4		External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREN	0: PC3 1: PD15 2: PB9 3: PC4	4: PC15 5: PF12	External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEN	0: PC5 1: PD14 2: PA13 3: PC2	4: PC14 5: PF11	External Bus Interface (EBI) NAND Write Enable output.
EBI_REN	0: PF5 1: PA14 2: PA12 3: PC0	4: PF9 5: PF5	External Bus Interface (EBI) Read Enable output.
EBI_VSNCR	0: PA10 1: PD10 2: PH2 3: PA3		External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEN	0: PF4 1: PA13 2: PC5 3: PB6	4: PF8 5: PF4	External Bus Interface (EBI) Write Enable output.
ETH_MDC	0: PB4 1: PD14 2: PC1 3: PA6		Ethernet Management Data Clock.

Table 5.24. ACMP1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP1Y	BUSACMP1X	Bus
PF14	PF15	PF15	PF14	PB14	PB15	PB15	PB14			CH31
	PF13	PF13			PB13	PB13				CH30
PF12			PF12	PB12			PB12			CH29
	PF11	PF11			PB11	PB11				CH28
PF10			PF10	PB10			PB10			CH27
	PF9	PF9			PB9	PB9				CH26
PF8			PF8							CH25
	PF7	PF7								CH24
PF6			PF6	PB6			PB6			CH23
	PF5	PF5			PB5	PB5				CH22
PF4			PF4	PB4			PB4			CH21
	PF3	PF3			PB3	PB3				CH20
PF2			PF2	PB2			PB2			CH19
	PF1	PF1			PB1	PB1				CH18
PF0			PF0	PB0			PB0			CH17
	PE15	PE15			PA15	PA15				CH16
PE14			PE14	PA14			PA14			CH15
	PE13	PE13			PA13	PA13				CH14
PE12			PE12	PA12			PA12			CH13
	PE11	PE11			PA11	PA11				CH12
PE10			PE10	PA10			PA10			CH11
	PE9	PE9			PA9	PA9				CH10
PE8			PE8	PA8			PA8			CH9
	PE7	PE7			PA7	PA7				CH8
PE6			PE6	PA6			PA6	PC15	PC15	CH7
	PE5	PE5			PA5	PA5		PC14	PC14	CH6
PE4			PE4	PA4			PA4	PC13	PC13	CH5
					PA3	PA3		PC12	PC12	CH4
				PA2			PA2	PC11	PC11	CH3
	PE1	PE1			PA1	PA1		PC10	PC10	CH2
PE0			PE0	PA0			PA0	PC9	PC9	CH1
								PC8	PC8	CH0

Table 5.27. ADC0 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSADC0Y	BUSADC0X	Bus
	PF15	PF15			PB15	PB15				CH31
PF14			PF14	PB14			PB14			CH30
	PF13	PF13			PB13	PB13				CH29
PF12			PF12	PB12			PB12			CH28
	PF11	PF11			PB11	PB11				CH27
PF10			PF10	PB10			PB10			CH26
	PF9	PF9			PB9	PB9				CH25
PF8			PF8							CH24
	PF7	PF7								CH23
PF6			PF6	PB6			PB6			CH22
	PF5	PF5			PB5	PB5				CH21
PF4			PF4	PB4			PB4			CH20
	PF3	PF3			PB3	PB3				CH19
PF2			PF2	PB2			PB2			CH18
	PF1	PF1			PB1	PB1				CH17
PF0			PF0	PB0			PB0			CH16
	PE15	PE15			PA15	PA15				CH15
PE14			PE14	PA14			PA14			CH14
	PE13	PE13			PA13	PA13				CH13
PE12			PE12	PA12			PA12			CH12
	PE11	PE11			PA11	PA11				CH11
PE10			PE10	PA10			PA10			CH10
	PE9	PE9			PA9	PA9				CH9
PE8			PE8	PA8			PA8			CH8
	PE7	PE7			PA7	PA7		PD7	PD7	CH7
PE6			PE6	PA6			PA6	PD6	PD6	CH6
	PE5	PE5			PA5	PA5		PD5	PD5	CH5
PE4			PE4	PA4			PA4	PD4	PD4	CH4
					PA3	PA3		PD3	PD3	CH3
				PA2			PA2	PD2	PD2	CH2
	PE1	PE1			PA1	PA1		PD1	PD1	CH1
PE0			PE0	PA0			PA0	PD0	PD0	CH0

Table 5.31. VDAC0 / OPA Bus and Pin Mapping

OPA0_P							
APORT4X	APORT3X	APORT2X	APORT1X	APORT4Y	APORT3Y	APORT2Y	APORT1Y
BUSDY	BUSCX	BUSBX	BUSAX	BUSDY	BUSCY	BUSBY	BUSAY
PF15		PB15			PF15		PB15
	PF14		PB14	PF14		PB14	
PF13		PB13			PF13		PB13
	PF12		PB12	PF12		PB12	
PF11		PB11			PF11		PB11
	PF10		PB10	PF10		PB10	
PF9		PB9			PF9		PB9
	PF8			PF8			
PF7					PF7		
	PF6		PB6	PF6		PB6	
PF5		PB5			PF5		PB5
	PF4		PB4	PF4		PB4	
PF3		PB3			PF3		PB3
	PF2		PB2	PF2		PB2	
PF1		PB1			PF1		PB1
	PF0		PB0	PF0		PB0	
PE15		PA15			PE15		PA15
	PE14		PA14	PE14		PA14	
PE13		PA13			PE13		PA13
	PE12		PA12	PE12		PA12	
PE11		PA11			PE11		PA11
	PE10		PA10	PE10		PA10	
PE9		PA9			PE9		PA9
	PE8		PA8	PE8		PA8	
PE7		PA7			PE7		PA7
	PE6		PA6	PE6		PA6	
PE5		PA5			PE5		PA5
	PE4		PA4	PE4		PA4	
		PA3					PA3
			PA2			PA2	
PE1		PA1			PE1		PA1
	PE0		PA0	PE0		PA0	

OPA0_N																																	
Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0

7. BGA152 Package Specifications

7.1 BGA152 Package Dimensions

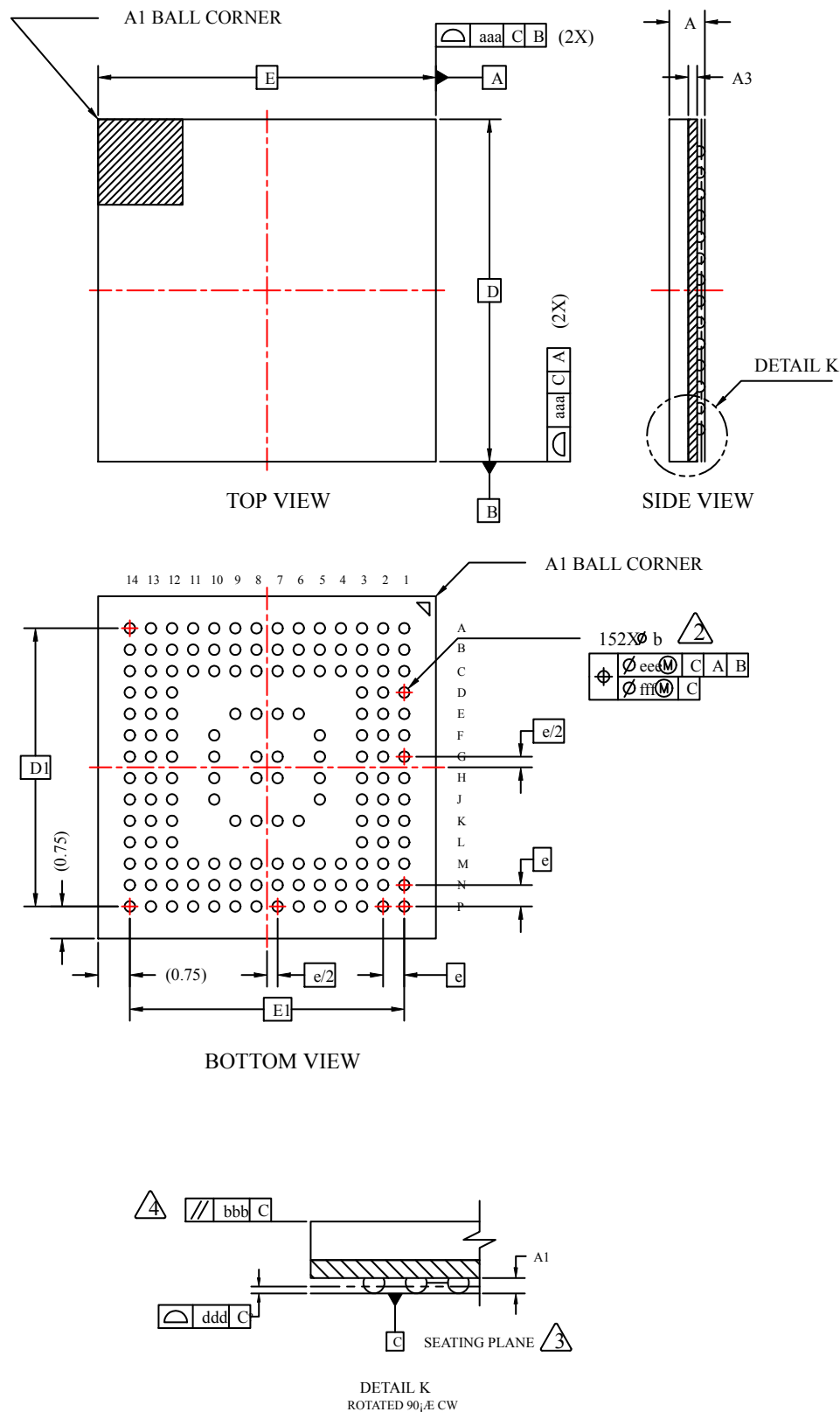


Figure 7.1. BGA152 Package Drawing